

ABSTRACT OF THE DISCLOSURE

A method to solder flex circuits by diode laser. First and second flex circuits composed of polymer flex substrate are provided. Each flex circuit has a top and a bottom side and at least one contact trace embedded in its surface. An area of solder is provided on the contact trace of at least one of the flex circuits and the flex circuits are positioned so that the contact traces of each flex circuit are substantially aligned. A laser beam is positioned to heat the contact trace to melt the solder and fuse the contacts.

10